



## General Description

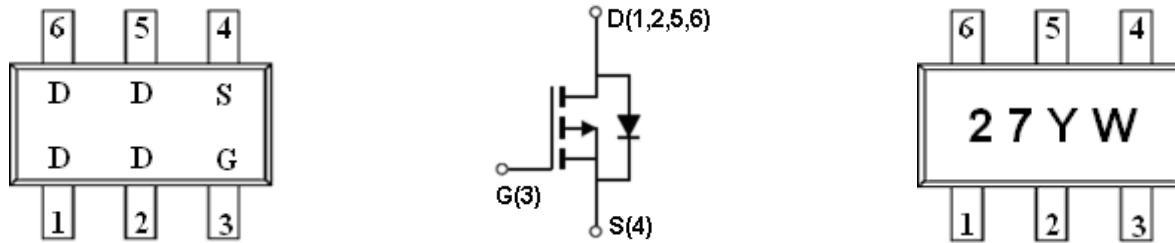
AFP1427, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

- -20V/-4.0A,  $R_{DS(ON)}=48m\Omega$ @ $V_{GS}=4.5V$
- -20V/-3.2A,  $R_{DS(ON)}=58m\Omega$ @ $V_{GS}=2.5V$
- -20V/-2.8A,  $R_{DS(ON)}=78m\Omega$ @ $V_{GS}=1.8V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-363 package design

## Pin Description ( SOT-363 )



## Application

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Net Working System

## Pin Define

Pin	Symbol	Description
1	D	Drain
2	D	Drain
3	G	Gate
4	S	Source
5	D	Drain
6	D	Drain

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP1427S36RG	27YW	SOT-363	Tape & Reel	3000 EA

※ 27 parts code

※ Y year code ( 0 ~ 9 )

※ W week code ( A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52 )

※ AFP1427S36RG : 7" Tape & Reel ; Pb-Free ; Halogen-Free



### Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DSS}$	-20	V
Gate -Source Voltage	$V_{GSS}$	$\pm 12$	V
Continuous Drain Current( $T_J=150^\circ\text{C}$ )	$I_D$	-3.0	A
$T_A=70^\circ\text{C}$		-2.0	
Pulsed Drain Current	$I_{DM}$	-8	A
Continuous Source Current(Diode Conduction)	$I_S$	-1.4	A
Power Dissipation	$P_D$	1.5	W
$T_A=70^\circ\text{C}$		1.0	
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{eJA}$	120	$^\circ\text{C}/\text{W}$

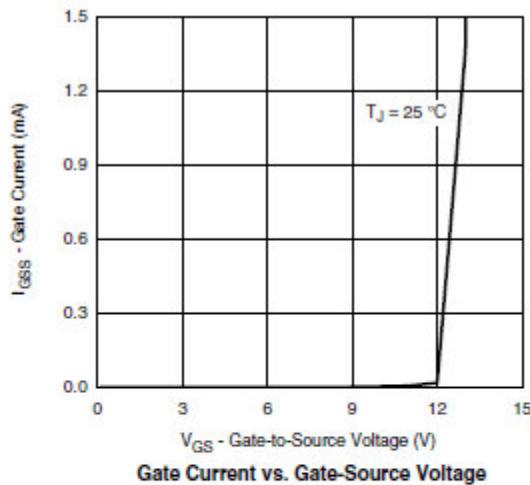
### Electrical Characteristics

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

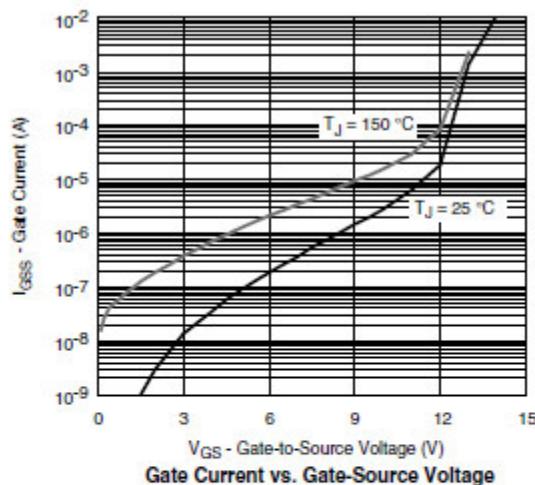
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-20			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.4		-0.8	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-16\text{V}, V_{GS}=0\text{V}$			-1	uA
		$V_{DS}=-16\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$			-10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq -5\text{V}, V_{GS}=-4.5\text{V}$	-6			A
		$V_{DS} \geq -5\text{V}, V_{GS}=-2.5\text{V}$	-4			
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5\text{V}, I_D=-4.0\text{A}$		38	48	m $\Omega$
		$V_{GS}=-2.5\text{V}, I_D=-3.2\text{A}$		48	58	
		$V_{GS}=-1.8\text{V}, I_D=-2.8\text{A}$		63	78	
Forward Transconductance	$g_{FS}$	$V_{DS}=-5\text{V}, I_D=-3.6\text{A}$		10		S
Diode Forward Voltage	$V_{SD}$	$I_S=-1.6\text{A}, V_{GS}=0\text{V}$		-0.85	-1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=-10\text{V}, V_{GS}=-4.5\text{V}$ $I_D=-4.0\text{A}$		8.0	12	nC
Gate-Source Charge	$Q_{gs}$			0.9		
Gate-Drain Charge	$Q_{gd}$			3.0		
Input Capacitance	$C_{iss}$	$V_{DS}=-10\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		780		pF
Output Capacitance	$C_{oss}$			115		
Reverse Transfer Capacitance	$C_{rss}$			55		
Turn-On Time	$t_{d(on)}$	$V_{DD}=-10\text{V}, R_L=2.3\Omega$ $I_D=-4.0\text{A}, V_{GEN}=-4.5\text{V}$ $R_G=1\Omega$		0.2	0.3	us
	$t_r$			1.0	1.5	
Turn-Off Time	$t_{d(off)}$			4.0	6.0	
	$t_f$			2.0	3.0	



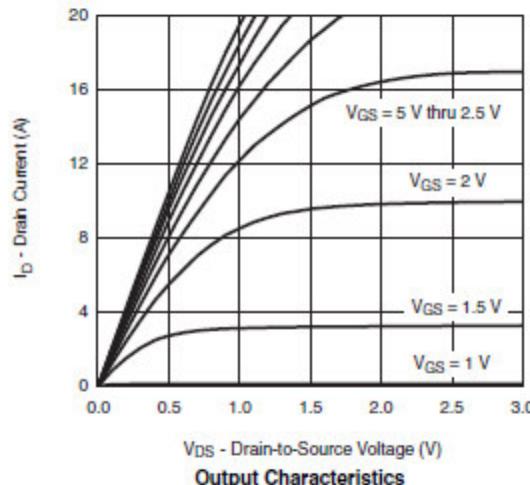
### Typical Characteristics



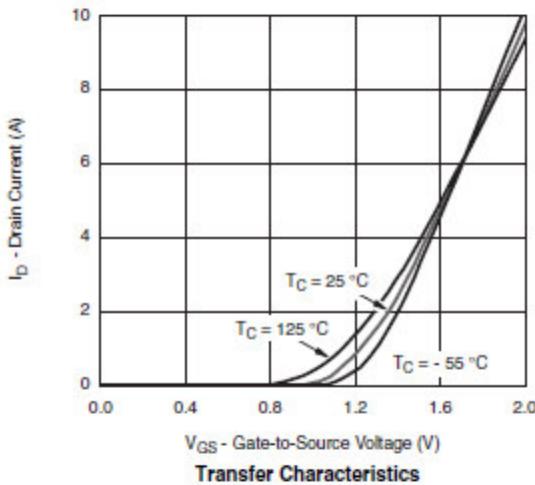
Gate Current vs. Gate-Source Voltage



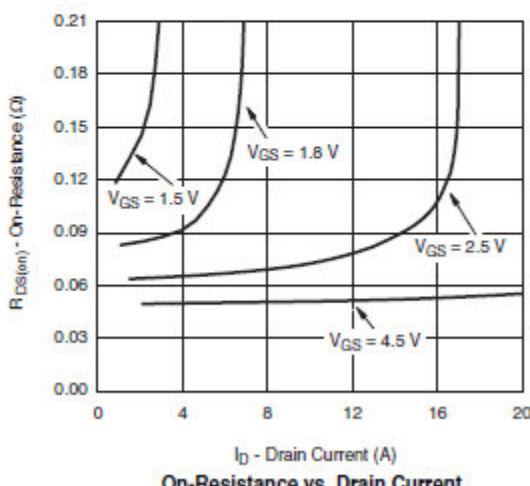
Gate Current vs. Gate-Source Voltage



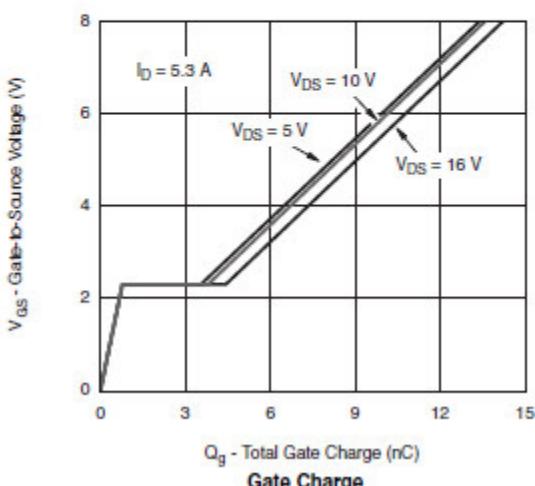
Output Characteristics



Transfer Characteristics



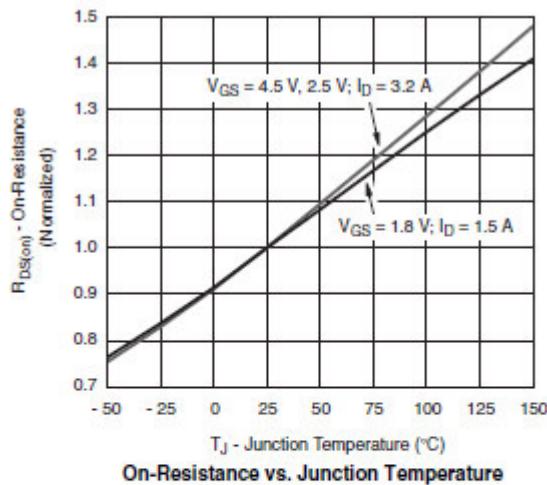
On-Resistance vs. Drain Current



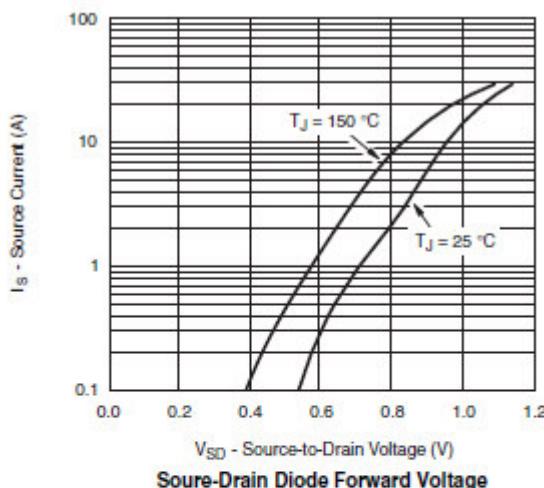
Gate Charge



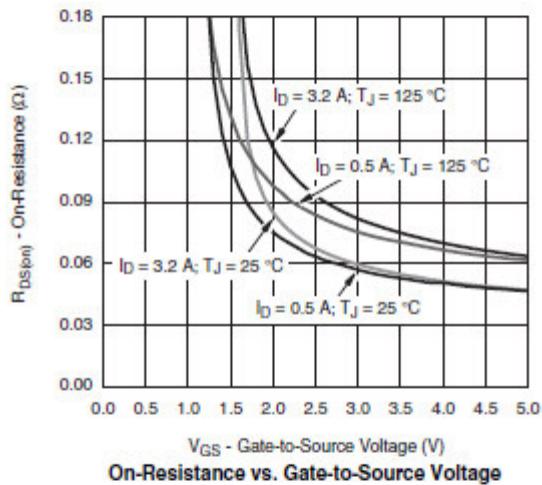
### Typical Characteristics



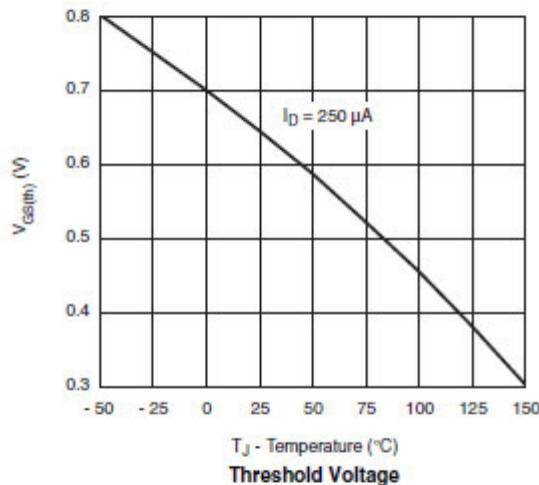
On-Resistance vs. Junction Temperature



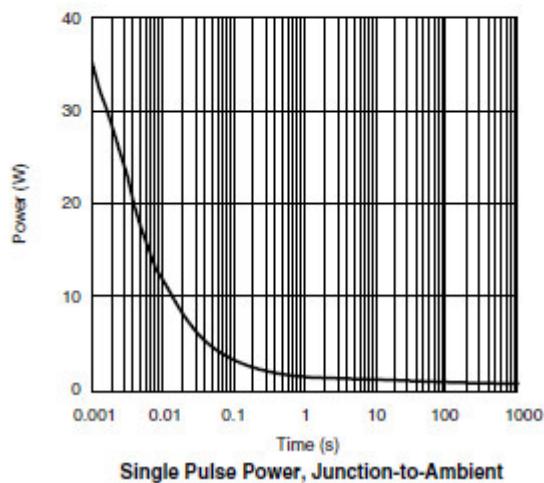
Source-Drain Diode Forward Voltage



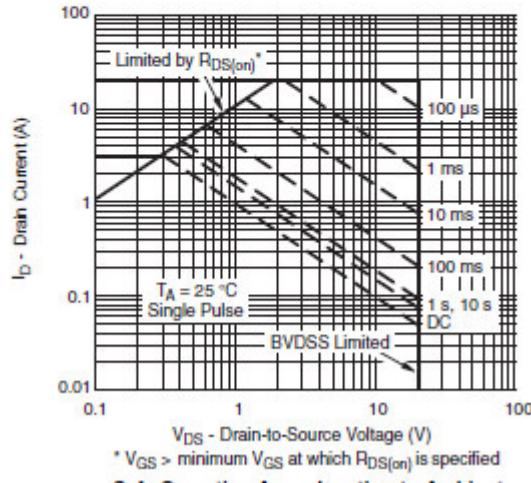
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

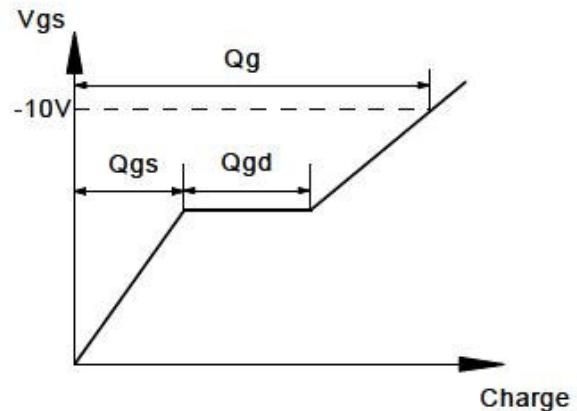
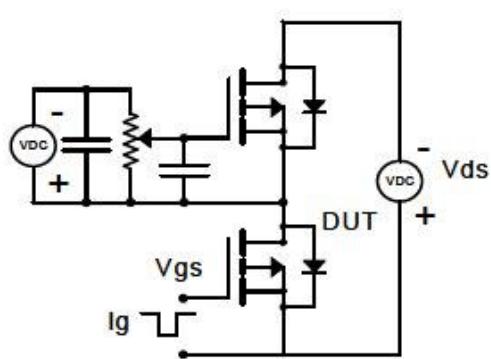


Safe Operating Area, Junction-to-Ambient

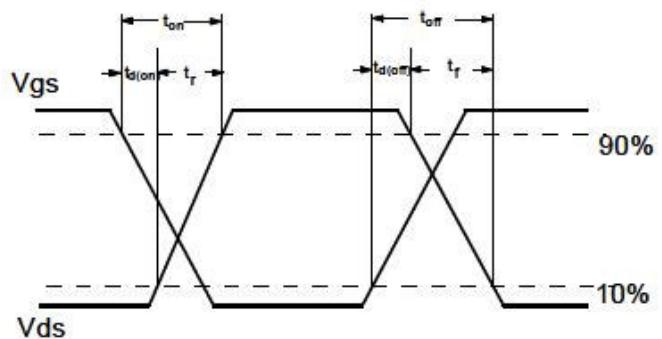
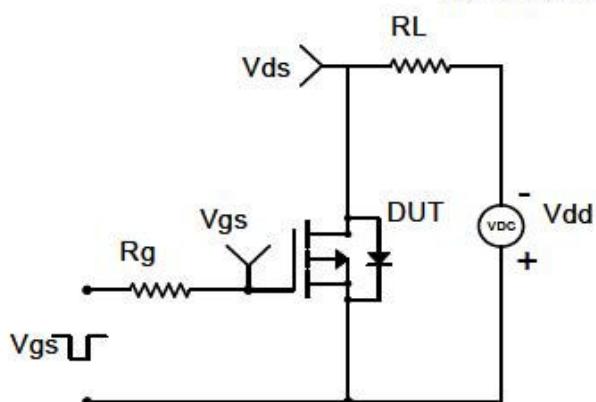


### Typical Characteristics

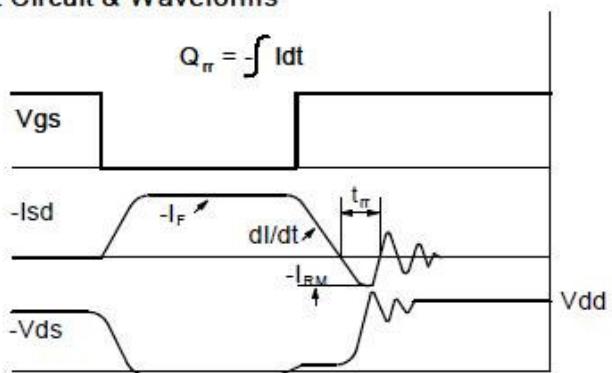
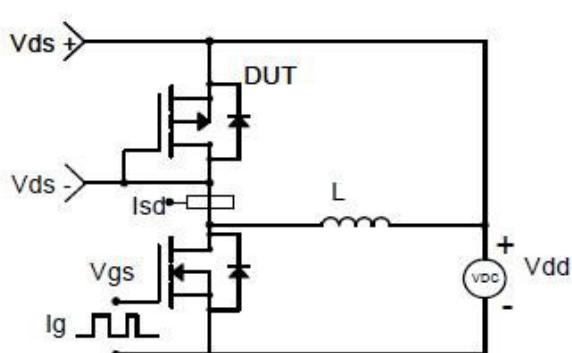
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

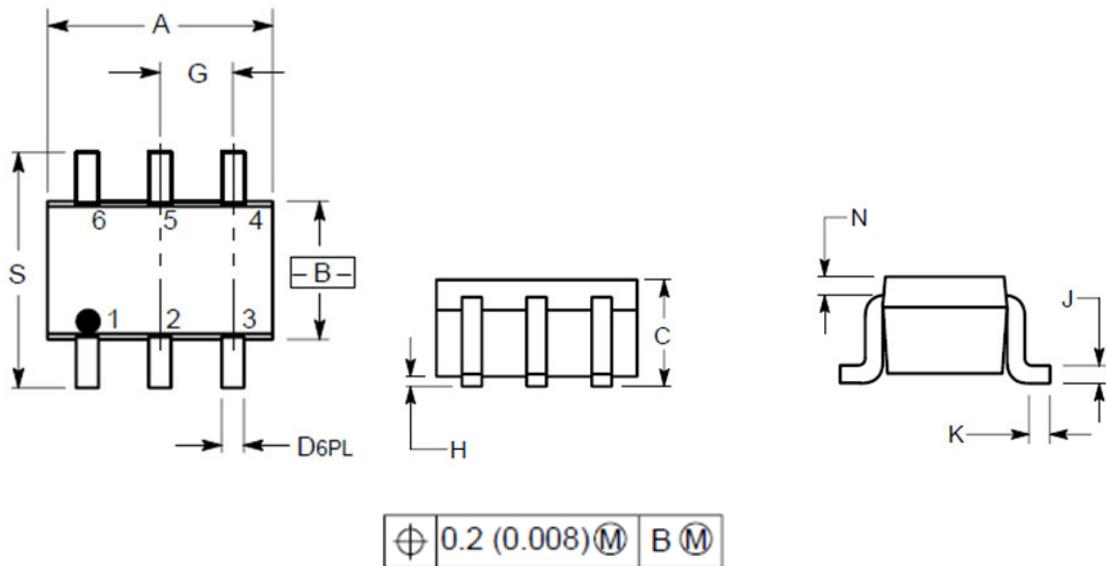




**Alfa-MOS  
Technology**

**AFP1427  
20V P-Channel  
Enhancement Mode MOSFET**

**Package Information ( SOT-363 )**



⊕ 0.2 (0.008) M B M

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

©2010 Alfa-MOS Technology Corp.  
2F, No.80, Sec.1, Cheng Kung Rd., Nan Kang Dist., Taipei City 115, Taiwan (R.O.C.)  
Tel : 886 2) 2651 3928  
Fax : 886 2) 2786 8483  
©<http://www.alfa-mos.com>